


THERMAL PASTE

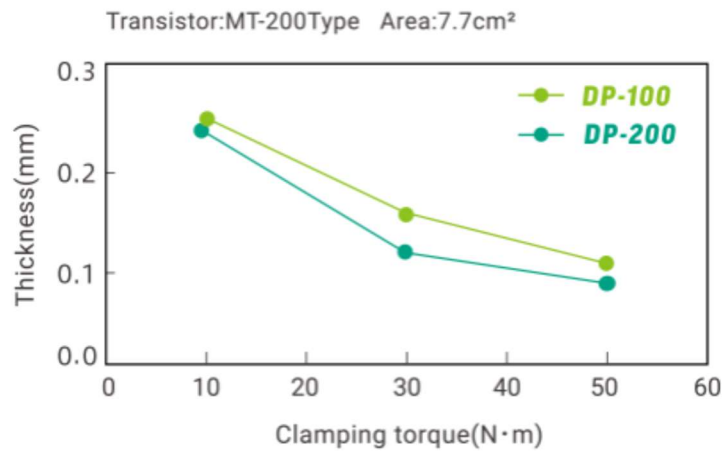
series: DP



- Eliminates air gaps between heat source and heat sink.
- High thermal conductivity of up to 6.5w/mk.
- Molecular structure prevents leakage and vaporization.
- Long term reliability.
- Good electrical insulation.
- Low rebound reduces load on electronic components.
- Compresses easily, absorbing dimensional tolerances.
- Typical applications include PCBs in automotive navigation systems, CIDs and ECUs, tablet devices, digital cameras, digital signage and manufacturing equipment.

Properties		DP-100	DP-200
Thermal Conductivity (W/m-k) – Our tests		6.5	4.8
Hot wire method		2.0	1.6
Hardness (Cone Penetration (1/10mm), not mixed)		51	55
Appearance		Gray	Gray
Specific Gravity		2.8	2.6
Volume Resistivity (Ω .cm)		5.9x10	7.2x10
Dielectric Breakdown Strength (kV/mm)		5.0	5.6
Dielectric Constant <50Hz>		8.9	7.6
<1KHz>		7.8	6.7
<1MHz>		7.0	6.6
Dielectric Dissipation Factor <50Hz>		0.234	0.017
<1KHz>		0.061	0.007
<1MHz>		0.015	0.005
Thermal Resistance ($^{\circ}$ C/W) Transistor: MT-200 Heat Input: 20V	Thickness (mm) 0.10	-	0.13
	0.15	0.13	-
	0.20	0.15	0.17
	0.30	0.18	0.22
Low Molecular Weight Siloxane Level D4-10 (ppm)	Solvent Extraction Method	Less than 700	Less than 900
	Head Space Method	Less than 1	Less than 3
Temperature Range ($^{\circ}$ C)		-40 ~ 200	-40 ~ 200

Clamping Torque Dependency



Thermal Resistance

Thickness (mm)	0.10	0.15	0.20	0.30
DP-100	-	0.13	0.15	0.18
DP-200	0.13	-	0.17	0.22

Transistor: MT-200Type
Heat input: 20V
(°C)